



**Value is the Difference**

## Northern Mexico Operations

Tijuana, Mexico

Suntron's Tijuana site of 79,000 square feet, offers a reduced cost solution without sacrificing quality. Suntron's Tijuana Operations focuses on high mix, high velocity electronics manufacturing services, specializing in quick turn assembly of printed circuit cards, cable and harnesses, wire wrap backplanes, and box build. End markets served include a variety of high-reliability industrial, aerospace and defense applications.

Look to Suntron to support your ITAR Registered products within this Low Cost Region (LCR).

### Market Segment Supported

- Aerospace & Defense
- Industrial
- Networking & Telecommunications

### Certifications

- AS 9100
- ISO 9001 : 2000
- J-STD-001
- IPC-A-610 Class II, III
- IPC 620A
- ITAR Registered
- UL/CSA
- Certified for Lead-free Manufacturing for both SMT and PTH (RoHS)

### Require more information?

If you have questions or would like to obtain further information, please call 888.520.3382 or email us at: [sales@suntroncorp.com](mailto:sales@suntroncorp.com)

### Scope of Services

- Product design capabilities
- Highly experienced New Product Introduction resources and comprehensive detailed processes committed to smooth transition of new products into production
- Rigorous First Article Inspection Process
- PCB assembly: PTH, SMT, and mixed technology
- BGA and fine pitch assembly: high density interconnection capabilities down to 15-mil fine pitch and high I/O BGA's
- Highly skilled workforce: assembly personnel receive IPC-A-610 and J-STD training and periodic refresher training by internal IPC certified trainers
- Focus on high mix, low to medium volume manufacturing
- Continuous flow PCBA assembly with five SMT lines
- Complex cable/harness assembly using both military and commercial connectors and multi-conductor, shielded twisted pair wire
- Cable and harness assembly supporting both high and low volume production
- Coaxial RF cable assembly
- Hand-lacing complex cables/harnesses
- Manufacturing capability to build complex back plane assemblies including wire wrap capabilities
- Complex electronic and electro mechanical assemblies
- Integration of electrical and mechanical sub-components into the final system or product
- Box Build, system integration, configure to order, and direct delivery to end user
- Test engineering: design for testability (DFT) analysis, in-circuit and functional test development
- Custom manufacturing tests including: Functional tests of PCBA, ICT
- Continuity, diagnostic, and hi-pot testing using Eclipse and Cirrus test systems
- In-circuit test (ICT)
- Automated X-ray laminography inspection
- Conformal coating system – Humiseal
- Supply chain management – EDI with all major suppliers
- Oracle ERP System with APS Kinaxis Simulation Capability
- Turnkey / Bonded Inventory
- Low cost region product and process transfer capabilities
- Depot Repair (out of warranty repair)